ELECTRICAL CHARACTERISTICS (T_j=25 unless otherwise specified)

Symbol	Test Condition	Quadrant	Value		Unit
I_{GT}	V_D=12V R_L=33	- -	MAX.	50	mA
				70	
V_{GT}		ALL	MAX.	1	V
V_{GD}	V_D=V_{DRM} T_j=125 R_L=3.3k	ALL	MIN.	0.2	V
I_L	I_G=1.2I_{GT}	- -	MAX.	50	mA
				100	
I_H	I_T=200mA		MAX.	60	mA
dV/dt	V_D=400V Gate Open T_j=125		MIN.	1200	V s
(dV/dt)c	(dI/dt)c=3.5A/ms, T_j=125		MIN.	12	9 V
t_{on}	I_G=80mA I_A=400mA I_R=40mA T_j=25		TYP.	5	s
t_{off}				30	

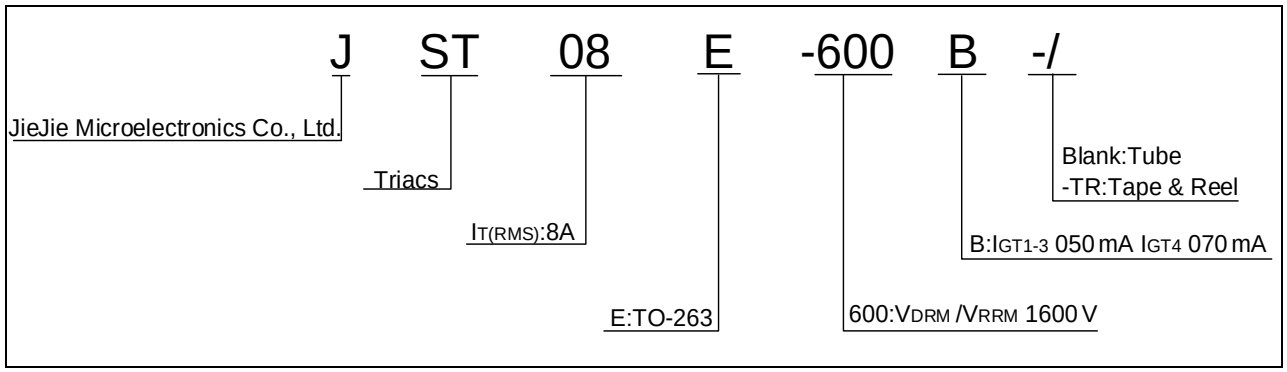
STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX.)	Unit
V_{TM}	I_{TM}=11A t_p=380 s	T_j=25	1.5	V
V_{TO}	Threshold voltage	T_j=125	0.81	V
R_D	Dynamic resistance	T_j=125	44	P
I_{DRM}	V_D=V_{DRM} V_R=V_{RRM}	T_j=25	5	A
I_{RRM}		T_j=125	0.25	mA

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	junction to case (AC)	1.6	/W
$R_{th(j-a)}$	junction to ambient (AC, in free air, S=2cm^2)	45	/W

ORDERING INFORMATION



MARKING

FIG.1: Maximum power dissipation versus RMS on-state current

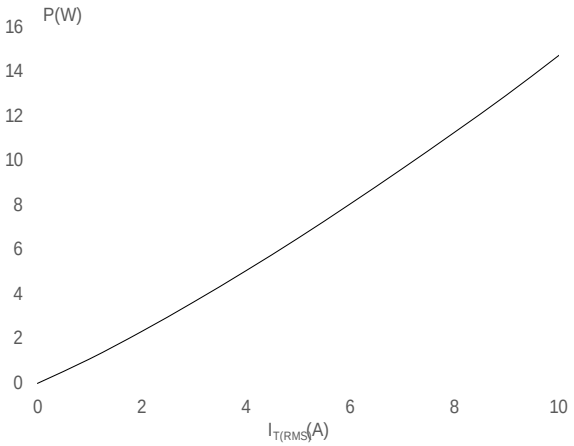


FIG.2: RMS on-state current versus case temperature

FIG.3: RMS on-state current versus ambient temperature (printed circuit board FR4,copper ° Â N € Ð ' ¹Ð Â ' • ¢ÆO.8 0 ` ` ,8 € FIG.4: Surge peak on-state current versus number of cycles

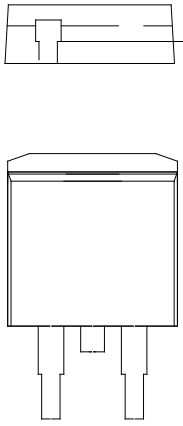
FIG.7: Relative variations of gate trigger current, holding current and latching current versus junction temperature



ORDERING INFORMATION

Order code	

PACKAGE MECHANICAL DATA



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.40		9.60	0.370		0.378
D	2.40			0.094		
E	1.20		1.50	0.047		0.059
F	0.75		0.85	0.029		0.033

DELIVERY MODE

